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# JAN 30 2006

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:	
Chen, et al.	Confirmation No.: 9818
Serial No.: 10/810,965	Examiner: Trinh, Hoa B.
Filed: March 26, 2004	Group Art Unit; 2814
For: Novel Method to Improve Bump Reliability for )	
Flip Chip Device	Top-Team: 0503-A30731US

#### CERTIFICATE OF FACSIMILE TRANSMISSION UNDER 37 CFR §1.8

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted on the date indicated below via facsimile to the United States Patent and Trademark Office, Technology Group 2100, facsimile number (571) 273-8300. Total number of pages in this transmission 12.

January 30, 2006

Date

Daniel R. McClurc

### AMENDMENT AND RESPONSE TO OFFICE ACTION

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

The Office Action mailed November 15, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.